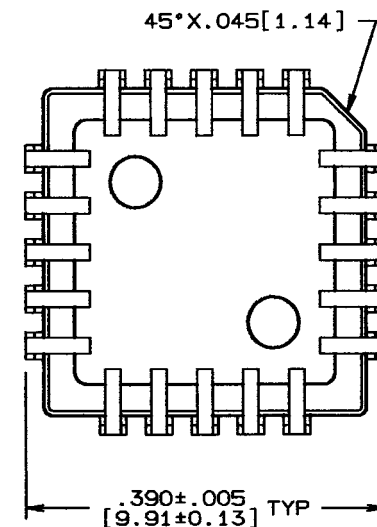
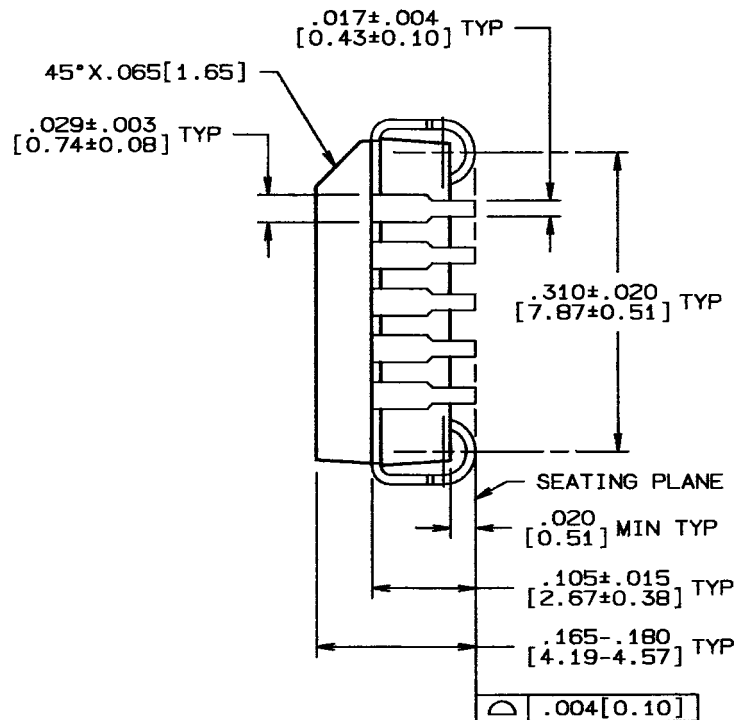
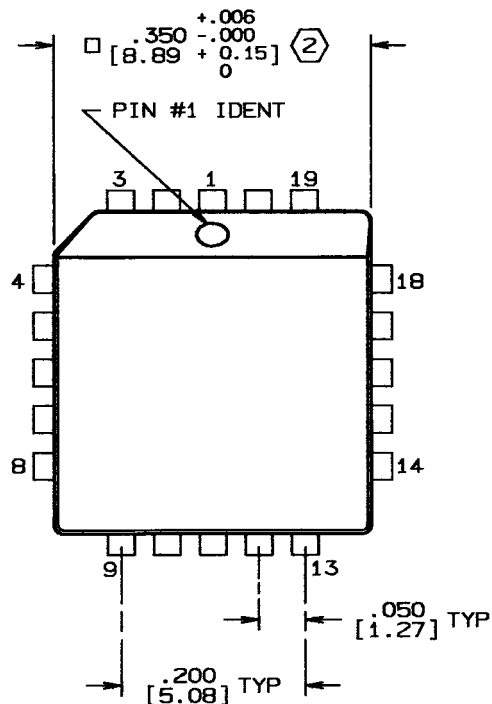




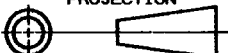
CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES / 5.08 MICROMETERS MINIMUM
SOLDER THICKNESS PER SIDE ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION .010 IN / 0.25mm
PER SIDE.
- REFERENCE JEDEC REGISTRATION MO-047, VARIATION AA,
DATED 5/90.

REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
K	REVISE & REDRAW TO STD FORMAT	09318	09/17/92	DEG/SL
L	ADD COPLANARITY & SEATING PLANE, CONVERT LIMIT DIM'S TO NOM±TOL. DIM 45°X.065 [1.65] WAS 45°X.065 [1.14]; DIM .390±.005 WAS .385-3.95	10036	12/01/93	MS/SL

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN		D. E. GRADY	09/17/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.		<i>Maui</i>	12/03/93	PLASTIC CHIP CARRIER, SQ., .050 LD PITCH, 20 LEAD		
ENGR. CHK.		<i>Sam Lion</i>	12/01/93			
APPROVAL						
PROJECTION						
INCH [MM]		SCALE		SIZE	DRAWING NUMBER	REV
		N/A		B	MKT-V20A	L
		DO NOT SCALE DRAWING			SHEET	1 OF 1